

## FEATURES

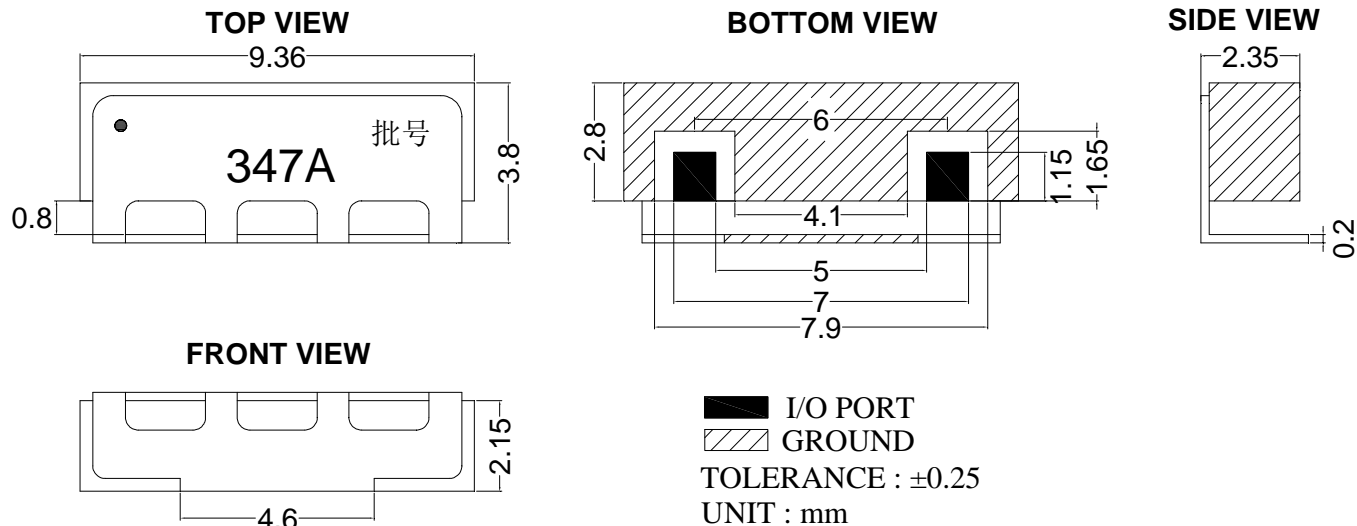
- Small Size,Light weight
- SMT package soldering
- Ideal for Microwave telecommunication

## SPECIFICATIONS

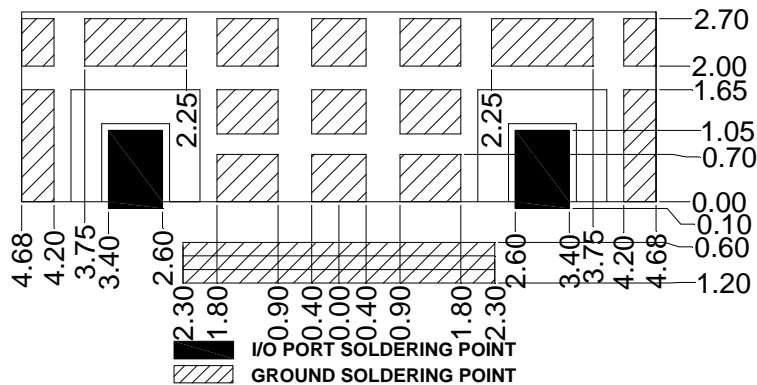
NO.	ITEM	TYP	SPEC	UNIT
1	Center Frequency [fo]	6525		MHz
2	Bandwidth [BW]	fo±600[5925~7125]		MHz
3	Insertion Loss in BW	3.6	4.8 max.@5925~5945 MHz	dB
		2.6	3.0 max.@5945~5955 MHz	
		2.3	2.7 max.@5955~7125 MHz	
4	Ripple in BW	1.8	2.0 max.@5925~5955 MHz	dB
		1.8	2.2 max.@5955~6095 MHz	
		1.8	2.5 max.@6095~7125 MHz	
5	Return Loss in BW	11.0	9.6 min.@5925~7125 MHz	dB
6	Attenuation[Absolute Value]	55	50 min. @ DC~5640 MHz	dB
		48	45 min. @ 5640~5835 MHz	
		30	15 min. @ 11890&14210 MHz	
		/	10 min. @ 17835&21315 MHz	

^ All Parameters are measured with 50Ω system at +25°C if not specified.

OUTLINE DRAWING



FOOTPRINT



**ABSOLUTE MAXIMUM RATINGS**

<b>Operation Temperature</b>	-40°C to +100°C
<b>Storage Temperature</b>	-40°C to +85°C
<b>Input Power</b>	1W

**NOTES**

- RoHS 2.0/HSF
- Reflow soldering temperature curve

